



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	HCS12X
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, EBI/EMI, I ² C, IrDA, LINbus, SCI, SPI
Peripherals	LCD, Motor control PWM, POR, PWM, WDT
Number of I/O	88
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912xhy128f0vlm

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Chapter 17 Liquid Crystal Display (LCD40F4BV2)547
Chapter 18 256 KByte Flash Module (S12XFTMR256K1V1)
Chapter 19 128 KByte Flash Module (S12XFTMR128K1V1)619
Chapter 20 Motor Controller (MC10B8CV1)667
Chapter 21 Stepper Stall Detector (SSDV1)699
Appendix A Electrical Characteristics717
Appendix B Package and Die Information
Appendix C PCB Layout Guidelines
Appendix D Derivative Differences
Appendix E Detailed Register Address Map768
Appendix F Ordering Information

Version Number	Revision Date	Effective Date	Author	Description of Changes
0.10	03 Jun 2010			fix on page 2-146, no open drain output when portV route to IIC fix Table 2-1., "Pin Functions and Priorities, PM[1:0] connect to SCI
0.11	15 Nov 2010			add NCLKX2 bit on ECLKCTL register2.3.10/2-91 fix typo,it is PTIM and PTM 2.3.16/2-95 remove Reduced drive at section 2.4.2.4 and 2.3.2/2-84 fix table Table 2-1./2-67, PM[1:0] is for TXD/RXD fix table Table 2-16./2-97, PTTRR[4], PT4 instead of PT6

2.1 Introduction

2.1.1 Overview

The S12XHY Family Port Integration Module establishes the interface between the peripheral modules and the I/O pins for all ports. It controls the electrical pin properties as well as the signal prioritization and multiplexing on shared pins.

This document covers:

- Port A associated with the XLKS, **I**RQ, **X**IRQ interrupt inputs and API_EXTCLK. Also associated with the LCD driver output
- Port B used as general purpose I/O and LCD driver output(including BP and FP pins)
- Port R associated with 2 timer module port 4:0 inputs can be used as an external interrupt source. Also associated with the LCD driver output. PR also associated with the IIC and CAN1
- Port T associated with 2 timer module. Also associated with the LCD driver output. It can be used as external interrupt source
- Port S associated with 1 SPI module, 1 SCI module, 1 IIC module and 1 MSCAN, and PWM. Port 6-5and 3-2 can be used as an external interrupt source.
- Port P connected to the PWM, also associated with LCD driver output
- Port H associated with 1 SPI, 1 SCI. Also associated with LCD driver output
- Port M associated with SCI1 PWM and TIM
- Port AD associated with one 12-channel ATD module. It an be used as an external interrupt source
- Port U/V associated with the Motor driver output. Also PV3-0 associated with 1 SPI, 1 IIC and 4 PWM channels. PU0/PU2/PU4/PU6 and PV0/PV2/PV4/PV6 associated with TIM0 channels 0 -3 and TIM1 channels 0 -3

Most I/O pins can be configured by register bits to select data direction, to enable and select pull-up or pull-down devices. Port U/V have register bits to select the slew rate control.

NOTE

This document assumes the availability of all features (112-pin package option). Some functions are not available on lower pin count package options. Refer to the pin-out summary section.

Port Integration Module (S12XHYPIMV1)

Field	Description
3 DDRS	Port S data direction— This register controls the data direction of pin 3. This register configures pin as either input or output. If CAN is enabled, it will force the pin as output.
	1 Associated pin is configured as output. 0 Associated pin is configured as input.
2 DDRS	Port S data direction— This register controls the data direction of pin 2. This register configures pin as either input or output. If CAN is enabled, it will force the pin as input.
	1 Associated pin is configured as output. 0 Associated pin is configured as input.
1 DDRS	Port S data direction— This register controls the data direction of pin 1. This register configures pin as either input or output. If SCI is enabled, it will force the pin as output Else if PWM7 is routing to PS1 and use as PWM channel output, it will force pin as output. If use as PWM emergency shut down, it will force pin as input.
	1 Associated pin is configured as output. 0 Associated pin is configured as input.
0 DDRS	Port S data direction— This register controls the data direction of pin 0. This register configures pin as either input or output. If SCI is enabled, it will force the pin as input Else if PWM6 is routing to PS0 and PWM6 is enabled, it will force pin as output.
	1 Associated pin is configured as output. 0 Associated pin is configured as input.

NOTE

Due to internal synchronization circuits, it can take up to 2 bus clock cycles until the correct value is read on PTS or PTIS registers, when changing the DDRS register.

2.3.25 PIM Reserved Registers



¹ Read: Anytime.

Write: Anytime.

	Mode				
Pulse	STOP	STOP ¹			
		Unit			
Ignored	$t_{pulse} \le 3$	bus clocks	$t_{pulse} \le t_{pign}$		
Uncertain	3 < t _{pulse} < 4	bus clocks	t _{pign} < t _{pulse} < t _{pval}		
Valid	$t_{pulse} \ge 4$	bus clocks	$t_{pulse} \ge t_{pval}$		

Table 2-81. Pulse Detection Criteria

¹These values include the spread of the oscillator frequency over temperature, voltage and process.



Figure 2-96. Pulse Illustration

A valid edge on an input is detected if 4 consecutive samples of a passive level are followed by 4 consecutive samples of an active level directly or indirectly.

The filters are continuously clocked by the bus clock in RUN and WAIT mode. In STOP mode the clock is generated by an RC-oscillator in the Port Integration Module. To maximize current saving the RC oscillator runs only if the following condition is true on any pin individually:

Sample count <= 4 and interrupt enabled (PIE=1) and interrupt flag not set (PIF=0).

2.5 Initialization Information

2.5.1 Port Data and Data Direction Register writes

It is not recommended to write PORTx/PTx and DDRx in a word access. When changing the register pins from inputs to outputs, the data may have extra transitions during the write access. Initialize the port data register before enabling the outputs.

Interrupt (S12XINTV2)



= Unimplemented or Reserved

Figure 4-13. Interrupt Request Configuration Data Register 7 (INT_CFDATA7) 1. Please refer to the notes following the PRIOLVL[2:0] description below.

Read: Anytime

Write: Anytime

Field	Description
2 CLKSW	Clock Switch — The CLKSW bit controls which clock the BDM operates with. It is only writable from a hardware BDM command. A minimum delay of 150 cycles at the clock speed that is active during the data portion of the command send to change the clock source should occur before the next command can be send. The delay should be obtained no matter which bit is modified to effectively change the clock source (either PLLSEL bit or CLKSW bit). This guarantees that the start of the next BDM command uses the new clock for timing subsequent BDM communications.
	 Table 5-4 shows the resulting BDM clock source based on the CLKSW and the PLLSEL (PLL select in the CRG module, the bit is part of the CLKSEL register) bits. Note: The BDM alternate clock source can only be selected when CLKSW = 0 and PLLSEL = 1. The BDM serial interface is now fully synchronized to the alternate clock source, when enabled. This eliminates frequency restriction on the alternate clock which was required on previous versions. Refer to the device specification to determine which clock connects to the alternate clock source input. Note: If the acknowledge function is turned on, changing the CLKSW bit will cause the ACK to be at the new rate for the write command which changes it. Note: In emulation modes (if modes available), the CLKSW bit will be set out of RESET.
1 UNSEC	 Unsecure — If the device is secured this bit is only writable in special single chip mode from the BDM secure firmware. It is in a zero state as secure mode is entered so that the secure BDM firmware lookup table is enabled and put into the memory map overlapping the standard BDM firmware lookup table. The secure BDM firmware lookup table verifies that the non-volatile memories (e.g. on-chip EEPROM and/or Flash EEPROM) are erased. This being the case, the UNSEC bit is set and the BDM program jumps to the start of the standard BDM firmware lookup table and the secure BDM firmware lookup table is turned off. If the erase test fails, the UNSEC bit will not be asserted. 0 System is in a secured mode. 1 System is in a unsecured mode. Note: When UNSEC is set, security is off and the user can change the state of the secure bits in the on-chip Flash EEPROM. Note that if the user does not change the state of the bits to "unsecured" mode, the system will be secured again when it is next taken out of reset. After reset this bit has no meaning or effect when the security byte in the Flash EEPROM is configured for unsecure mode.

PLLSEL	CLKSW	BDMCLK
0	0	Bus clock dependent on oscillator
0	1	Bus clock dependent on oscillator
1	0	Alternate clock (refer to the device specification to determine the alternate clock source)
1	1	Bus clock dependent on the PLL

Table 5-4. BDM Clock Sources

S12X Debug (S12XDBGV3) Module

SUB_1	BRN	*	; ;	JMP Destination address TRACE BUFFER ENTRY 1 RTI Destination address TRACE BUFFER ENTRY 3
ADDR1	NOP DBNE	A,PART5	; ;	Source address TRACE BUFFER ENTRY 4
IRQ_ISR	LDAB	#\$F0	;	IRQ Vector \$FFF2 = TRACE BUFFER ENTRY 2
	STAB RTI	VAR_C1	;	
	The	e execution flow taking int	0	account the IRQ is as follows
	LDX	#SUB_1		
MARK1	JMP	0,X	;	
IRQ_ISR	LDAB	#\$F0	;	
	STAB	VAR_C1		
	RTI		;	
SUB_1	BRN	*		
	NOP		;	
ADDR1	DBNE	A,PART5	;	

6.4.5.2.2 Loop1 Mode

Loop1 Mode, similarly to Normal Mode also stores only COF address information to the trace buffer, it however allows the filtering out of redundant information.

The intent of Loop1 Mode is to prevent the Trace Buffer from being filled entirely with duplicate information from a looping construct such as delays using the DBNE instruction or polling loops using BRSET/BRCLR instructions. Immediately after address information is placed in the Trace Buffer, the S12XDBG module writes this value into a background register. This prevents consecutive duplicate address entries in the Trace Buffer resulting from repeated branches.

Loop1 Mode only inhibits consecutive duplicate source address entries that would typically be stored in most tight looping constructs. It does not inhibit repeated entries of destination addresses or vector addresses, since repeated entries of these would most likely indicate a bug in the user's code that the S12XDBG module is designed to help find.

6.4.5.2.3 Detail Mode

In Detail Mode, address and data for all memory and register accesses is stored in the trace buffer. This mode also features information byte entries to the trace buffer, for each address byte entry. The information byte indicates the size of access (word or byte) and the type of access (read or write).

When tracing CPU12X activity in Detail Mode, all cycles are traced except those when the CPU12X is either in a free or opcode fetch cycle, the address range can be limited to a range specified by the TRANGE bits in DBGTCR. This function uses comparators C and D to define an address range inside which CPU12X activity should be traced (see Table 6-40). Thus the traced CPU12X activity can be restricted to particular register range accesses.

6.4.5.2.4 Pure PC Mode

In Pure PC Mode, tracing from the CPU the PC addresses of all executed opcodes, including illegal opcodes, are stored.



7.4.1.2 System Clocks Generator

Figure 7-16. System Clocks Generator

The clock generator creates the clocks used in the MCU (see Figure 7-16). The gating condition placed on top of the individual clock gates indicates the dependencies of different modes (STOP, WAIT) and the setting of the respective configuration bits.

The peripheral modules use the Bus Clock. Some peripheral modules also use the Oscillator Clock. If the MCU enters Self Clock Mode (see Section 7.4.2.2, "Self Clock Mode") Oscillator clock source is switched to PLLCLK running at its minimum frequency f_{SCM} . The Bus Clock is used to generate the clock visible at the ECLK pin. The Core Clock signal is the clock for the CPU. The Core Clock is twice the Bus Clock. But note that a CPU cycle corresponds to one Bus Clock.

IPLL clock mode is selected with PLLSEL bit in the CLKSEL register. When selected, the IPLL output clock drives SYSCLK for the main system including the CPU and peripherals. The IPLL cannot be turned off by clearing the PLLON bit, if the IPLL clock is selected. When PLLSEL is changed, it takes a maximum of 4 OSCCLK plus 4 PLLCLK cycles to make the transition. During the transition, all clocks freeze and CPU activity ceases.

Analog-to-Digital Converter (ADC12B12CV1) Block Description

¹If only AN0 should be converted use MULT=0.

10.3.2.2 ATD Control Register 1 (ATDCTL1)

Writes to this register will abort current conversion sequence.

Module Base + 0x0001



Figure 10-4. ATD Control Register 1 (ATDCTL1)

Read: Anytime

Write: Anytime

Field	Description
7 ETRIGSEL	External Trigger Source Select — This bit selects the external trigger source to be either one of the AD channels or one of the ETRIG3-0 inputs. See device specification for availability and connectivity of ETRIG3-0 inputs. If a particular ETRIG3-0 input option is not available, writing a 1 to ETRISEL only sets the bit but has not effect, this means that one of the AD channels (selected by ETRIGCH3-0) is configured as the source for external trigger. The coding is summarized in Table 10-5.
6–5 SRES[1:0]	A/D Resolution Select — These bits select the resolution of A/D conversion results. See Table 10-4 for coding.
4 SMP_DIS	 Discharge Before Sampling Bit No discharge before sampling. The internal sample capacitor is discharged before sampling the channel. This adds 2 ATD clock cycles to the sampling time. This can help to detect an open circuit instead of measuring the previous sampled channel.
3–0 ETRIGCH[3:0]	External Trigger Channel Select — These bits select one of the AD channels or one of the ETRIG3-0 inputs as source for the external trigger. The coding is summarized in Table 10-5.

	Table	10-4.	A/D	Resolution	Coding
--	-------	-------	-----	------------	--------

SRES1	SRES0	A/D Resolution
0	0	8-bit data
0	1	10-bit data
1	0	12-bit data
1	1	Reserved

13.3.2.5 PWM Center Align Enable Register (PWMCAE)

The PWMCAE register contains eight control bits for the selection of center aligned outputs or left aligned outputs for each PWM channel. If the CAEx bit is set to a one, the corresponding PWM output will be center aligned. If the CAEx bit is cleared, the corresponding PWM output will be left aligned. See Section 13.4.2.5, "Left Aligned Outputs" and Section 13.4.2.6, "Center Aligned Outputs" for a more detailed description of the PWM output modes.





Figure 13-7. PWM Center Align Enable Register (PWMCAE)

Read: Anytime

Write: Anytime

NOTE

Write these bits only when the corresponding channel is disabled.

Table 13-7. PWMCAE Field Descriptions

Field	Description
7–0	Center Aligned Output Modes on Channels 7–0
CAE[7:0]	0 Channels 7–0 operate in left aligned output mode.
	1 Channels 7–0 operate in center aligned output mode.

13.3.2.6 PWM Control Register (PWMCTL)

The PWMCTL register provides for various control of the PWM module.

Module Base + 0x0005





Read: Anytime

Write: Anytime

There are three control bits for concatenation, each of which is used to concatenate a pair of PWM channels into one 16-bit channel. When channels 6 and 7are concatenated, channel 6 registers become the high order bytes of the double byte channel. When channels 4 and 5 are concatenated, channel 4 registers become the high order bytes of the double byte channel. When channels 2 and 3 are concatenated, channel

When the transmit shift register is not transmitting a frame, the TXD pin goes to the idle condition, logic 1. If at any time software clears the TE bit in SCI control register 2 (SCICR2), the transmitter enable signal goes low and the transmit signal goes idle.

If software clears TE while a transmission is in progress (TC = 0), the frame in the transmit shift register continues to shift out. To avoid accidentally cutting off the last frame in a message, always wait for TDRE to go high after the last frame before clearing TE.

To separate messages with preambles with minimum idle line time, use this sequence between messages:

- 1. Write the last byte of the first message to SCIDRH/L.
- 2. Wait for the TDRE flag to go high, indicating the transfer of the last frame to the transmit shift register.
- 3. Queue a preamble by clearing and then setting the TE bit.
- 4. Write the first byte of the second message to SCIDRH/L.

14.4.5.3 Break Characters

Writing a logic 1 to the send break bit, SBK, in SCI control register 2 (SCICR2) loads the transmit shift register with a break character. A break character contains all logic 0s and has no start, stop, or parity bit. Break character length depends on the M bit in SCI control register 1 (SCICR1). As long as SBK is at logic 1, transmitter logic continuously loads break characters into the transmit shift register. After software clears the SBK bit, the shift register finishes transmitting the last break character and then transmits at least one logic 1. The automatic logic 1 at the end of a break character guarantees the recognition of the start bit of the next frame.

The SCI recognizes a break character when there are 10 or 11(M = 0 or M = 1) consecutive zero received. Depending if the break detect feature is enabled or not receiving a break character has these effects on SCI registers.

If the break detect feature is disabled (BKDFE = 0):

- Sets the framing error flag, FE
- Sets the receive data register full flag, RDRF
- Clears the SCI data registers (SCIDRH/L)
- May set the overrun flag, OR, noise flag, NF, parity error flag, PE, or the receiver active flag, RAF (see 3.4.4 and 3.4.5 SCI Status Register 1 and 2)

If the break detect feature is enabled (BKDFE = 1) there are two scenarios¹

The break is detected right from a start bit or is detected during a byte reception.

- Sets the break detect interrupt flag, BKDIF
- Does not change the data register full flag, RDRF or overrun flag OR
- Does not change the framing error flag FE, parity error flag PE.
- Does not clear the SCI data registers (SCIDRH/L)
- May set noise flag NF, or receiver active flag RAF.

^{1.} A Break character in this context are either 10 or 11 consecutive zero received bits

16.3.2.8 Timer Control Register 1/Timer Control Register 2 (TCTL1/TCTL2)



Write: Anytime

Module Base + 0x0008

Table 16-8. TCTL1/TCTL2 Field Descriptions

Field	Description
7:0 OMx	 Output Mode — These eight pairs of control bits are encoded to specify the output action to be taken as a result of a successful OCx compare. When either OMx or OLx is 1, the pin associated with OCx becomes an output tied to OCx. Note: To enable output action by OMx bits on timer port, the corresponding bit in OC7M should be cleared. For an output line to be driven by an OCx the OCPDx must be cleared.
7:0 OLx	 Output Level — These eight pairs of control bits are encoded to specify the output action to be taken as a result of a successful OCx compare. When either OMx or OLx is 1, the pin associated with OCx becomes an output tied to OCx. Note: To enable output action by OLx bits on timer port, the corresponding bit in OC7M should be cleared. For an output line to be driven by an OCx the OCPDx must be cleared.

Table 16-9. Compare Result Output Action

ОМх	OLx	Action
0	0	No output compare action on the timer output signal
0	1	Toggle OCx output line
1	0	Clear OCx output line to zero
1	1	Set OCx output line to one

Address & Name		7	6	5	4	3	2	1	0
0x000E	R	ECCR15	ECCR14	ECCR13	ECCR12	ECCR11	ECCR10	ECCR9	ECCR8
FECCRHI	w[
0x000F	R	ECCR7	ECCR6	ECCR5	ECCR4	ECCR3	ECCR2	ECCR1	ECCR0
FECCRLO	w								
0x0010	R	NV7	NV6	NV5	NV4	NV3	NV2	NV1	NV0
FOPT	w								
0x0011	R	0	0	0	0	0	0	0	0
FRSV2	w								
0x0012	R	0	0	0	0	0	0	0	0
FRSV3	w								
0x0013	R	0	0	0	0	0	0	0	0
FRSV4	w								
	[= Unimpleme	ented or Rese	erved				



18.3.1.1 Flash Clock Divider Register (FCLKDIV)

The FCLKDIV register is used to control timed events in program and erase algorithms.



All bits in the FCLKDIV register are readable, bits 6–0 are write once and bit 7 is not writable.

OSCCLK Frequency (MHz)		FDIV[6:0]	OSCCLK (M	OSCCLK Frequency (MHz)		
MIN ¹	MAX ²		MIN ¹	MAX ²		
1.60	2.10	0x01	33.60	34.65	0x20	
2.40	3.15	0x02	34.65	35.70	0x21	
3.20	4.20	0x03	35.70	36.75	0x22	
4.20	5.25	0x04	36.75	37.80	0x23	
5.25	6.30	0x05	37.80	38.85	0x24	
6.30	7.35	0x06	38.85	39.90	0x25	
7.35	8.40	0x07	39.90	40.95	0x26	
8.40	9.45	0x08	40.95	42.00	0x27	
9.45	10.50	0x09	42.00	43.05	0x28	
10.50	11.55	0x0A	43.05	44.10	0x29	
11.55	12.60	0x0B	44.10	45.15	0x2A	
12.60	13.65	0x0C	45.15	46.20	0x2B	
13.65	14.70	0x0D	46.20	47.25	0x2C	
14.70	15.75	0x0E	47.25	48.30	0x2D	
15.75	16.80	0x0F	48.30	49.35	0x2E	
16.80	17.85	0x10	49.35	50.40	0x2F	
17.85	18.90	0x11				
18.90	19.95	0x12				
19.95	21.00	0x13				
21.00	22.05	0x14				
22.05	23.10	0x15				
23.10	24.15	0x16				
24.15	25.20	0x17				
25.20	26.25	0x18				
26.25	27.30	0x19				
27.30	28.35	0x1A				
28.35	29.40	0x1B				
29.40	30.45	0x1C				
30.45	31.50	0x1D				
31.50	32.55	0x1E				
32.55	33.60	0x1F				

Table 18-5. FDIV vs OSCCLK Frequency

¹ FDIV shown generates an FCLK frequency of >0.8 MHz

² FDIV shown generates an FCLK frequency of 1.05 MHz

Register	Error Bit	Error Condition
FSTAT		Set if CCOBIX[2:0] != 101 at command launch
		Set if command not available in current mode (see Table 18-26)
	ACCERN	Set if an invalid global address [22:0] is supplied
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
	FPVIOL	Set if the global address [22:0] points to a protected area
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

Table 18-38. Program P-Flash Command Error Handling

18.4.2.6 Program Once Command

The Program Once command restricts programming to a reserved 64 byte field (8 phrases) in the nonvolatile information register located in P-Flash block 0. The Program Once reserved field can be read using the Read Once command as described in Section 18.4.2.4. The Program Once command must only be issued once since the nonvolatile information register in P-Flash block 0 cannot be erased. The Program Once command must not be executed from the Flash block containing the Program Once reserved field to avoid code runaway.

CCOBIX[2:0]	FCCOB Parameters				
000	0x07	Not Required			
001	Program Once phrase i	Program Once phrase index (0x0000 - 0x0007)			
010	Program Once word 0 value				
011	Program Once word 1 value				
100	Program Once word 2 value				
101	Program Once	e word 3 value			

Table 18-39. Program Once Command FCCOB Requirements

Upon clearing CCIF to launch the Program Once command, the Memory Controller first verifies that the selected phrase is erased. If erased, then the selected phrase will be programmed and then verified with read back. The CCIF flag will remain clear, setting only after the Program Once operation has completed.

The reserved nonvolatile information register accessed by the Program Once command cannot be erased and any attempt to program one of these phrases a second time will not be allowed. Valid phrase index values for the Program Once command range from 0x0000 to 0x0007. During execution of the Program Once command, any attempt to read addresses within P-Flash block 0 will return invalid data.

(as evidenced by the Memory Controller returning CCIF to 1). Some commands return information to the FCCOB register array.

The generic format for the FCCOB parameter fields in NVM command mode is shown in Table 19-21. The return values are available for reading after the CCIF flag in the FSTAT register has been returned to 1 by the Memory Controller. Writes to the unimplemented parameter fields (CCOBIX = 110 and CCOBIX = 111) are ignored with reads from these fields returning 0x0000.

Table 19-21 shows the generic Flash command format. The high byte of the first word in the CCOB array contains the command code, followed by the parameters for this specific Flash command. For details on the FCCOB settings required by each command, see the Flash command descriptions in Section 19.3.2.

CCOBIX[2:0]	Byte	FCCOB Parameter Fields (NVM Command Mode)
000	HI	FCMD[7:0] defining Flash command
000	LO	0, Global address [22:16]
001	HI Global address [15:8]	
001	LO	Global address [7:0] Data 0 [15:8] Data 0 [7:0]
010	HI	Data 0 [15:8]
010	LO	Data 0 [7:0]
011	н	Data 1 [15:8]
	LO	Data 1 [7:0]
100	н	Data 2 [15:8]
100	LO	Data 2 [7:0]
101	HI	Data 3 [15:8]
101	LO	Data 3 [7:0]

Table 19-21. FCCOB - NVM Command Mode (Typical Usage)

19.2.1.12 Flash Reserved0 Register (FRSV0)

This Flash register is reserved for factory testing.



Figure 19-15. Flash Reserved0 Register (FRSV0)

All bits in the FRSV0 register read 0 and are not writable.

Motor Controller (MC10B8CV1)



Motor Controller (MC10B8CV1)

Num	Rating	Symbol	Min	Мах	Unit
1	I/O, regulator and analog supply voltage	V _{DD35}	-0.3	6.0	V
2	Digital logic supply voltage ²	V _{DD}	-0.3	2.16	V
3	PLL supply voltage ²	V _{DDPLL}	-0.3	2.16	V
4	NVM supply voltage ²	V _{DDF}	-0.3	3.6	V
5	Voltage difference V _{DDX} to V _{DDA}	Δ_{VDDX}	-0.3	0.3	V
6	Voltage difference V _{SSX} to V _{SSA}	Δ_{VSSX}	-0.3	0.3	V
5	Voltage difference V _{DDM1,2} to V _{DDA}	$\Delta_{\rm VDDMA}$	-0.3	0.3	V
6	Voltage difference V _{SSM1,2} to V _{SSA}	$\Delta_{\rm VSSMA}$	-0.3	0.3	V
7	Digital I/O input voltage	V _{IN}	-0.3	6.0	V
8	Analog reference	V _{RH,} V _{RL}	-0.3	6.0	V
9	EXTAL, XTAL	V _{ILV}	-0.3	2.16	V
11	Instantaneous maximum current Single pin limit for all digital I/O pins ³	Ι _D	-25	+25	mA
12	Instantaneous maximum current Single pin limit for EXTAL, XTAL ⁴	I _{DL}	-25	+25	mA
14	Maximum current Single pin limit for power supply pins	I _{DV}	-100	+100	mA
15	Storage temperature range	T _{stg}	-65	155	°C

Table A-1. Absolute Maximum Ratings¹

Beyond absolute maximum ratings device might be damaged. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when the device is powered from an external source. All digital I/O pins are internally clamped to V_{SSX} and V_{DDX} , or V_{SSA} and V_{DDA} . Those pins are internally clamped to V_{SSPLL} and V_{DDPLL} . 2

3

ESD Protection and Latch-up Immunity A.1.6

All ESD testing is in conformity with CDF-AEC-Q100 stress test qualification for automotive grade integrated circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM) and the Charge Device Model.

A device will be defined as a failure if after exposure to ESD pulses the device no longer meets the device specification. Complete DC parametric and functional testing is performed per the applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Electrical Characteristics

is recommended to configure PortAD pins as outputs only for low frequency, low load outputs. The impact on ATD accuracy is load dependent and not specified. The values specified are valid under condition that no PortAD output drivers switch during conversion.

A.2.2.2 Source Resistance

Due to the input pin leakage current as specified in Table A-7 and Table A-6 in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S specifies results in an error (10-bit resolution) of less than 1/2 LSB (2.5 mV) at the maximum leakage current. If device or operating conditions are less than worst case or leakage-induced error is acceptable, larger values of source resistance of up to 10Kohm are allowed.

A.2.2.3 Source Capacitance

When sampling an additional internal capacitor is switched to the input. This can cause a voltage drop due to charge sharing with the external and the pin capacitance. For a maximum sampling error of the input voltage ≤ 1 LSB (10-bit resilution), then the external filter capacitor, $C_f \geq 1024 * (C_{INS}-C_{INN})$.

A.2.2.4 Current Injection

There are two cases to consider.

- 1. A current is injected into the channel being converted. The channel being stressed has conversion values of \$3FF (in 10-bit mode) for analog inputs greater than V_{RH} and \$000 for values less than V_{RL} unless the current is higher than specified as disruptive condition.
- 2. Current is injected into pins in the neighborhood of the channel being converted. A portion of this current is picked up by the channel (coupling ratio K), This additional current impacts the accuracy of the conversion depending on the source resistance.

The additional input voltage error on the converted channel can be calculated as:

 $V_{ERR} = K * R_S * I_{INJ}$

with I_{INJ} being the sum of the currents injected into the two pins adjacent to the converted channel.